

PARADIGM

256K Static RAM 64K x 4-Bit with Separate I/O

T. 46.23.10
PDM41251S/L
PDM41252S/L

Features

- Separate data input and output pins
- High speed access times
Com'l: 15, 20, 25, 35 and 45ns
Mil: 20, 25, 35, 45, and 55ns
- Low power operation
 - PDM41258S
Active: 400mW (typ.)
Standby: 400 μ W (typ.)
 - PDM41258L
Active: 350mW (typ.)
Standby: 100 μ W (typ.)
- PDM41251: output track inputs during write mode
- PDM41252: high impedance outputs during write mode
- TTL compatible inputs and outputs
- Military product MIL-STD-883, Rev. C
- Packages
Plastic dip - P
Cerdip - D, Plastic SOJ - SO,
Ceramic LCC - L28.

Description

The PDM41251 and PDM41252 are high performance CMOS static RAMs organized as 65,536 x 4 bits. This product is produced in Paradigm's proprietary CMOS technology which offers the designer the highest speed parts. Writing to this device is accomplished when the write enable ($\overline{WE}$) and the chip enable ($\overline{CE}$) inputs are both LOW. Reading is accomplished when $\overline{WE}$ remains HIGH and $\overline{CE}$ goes to LOW.

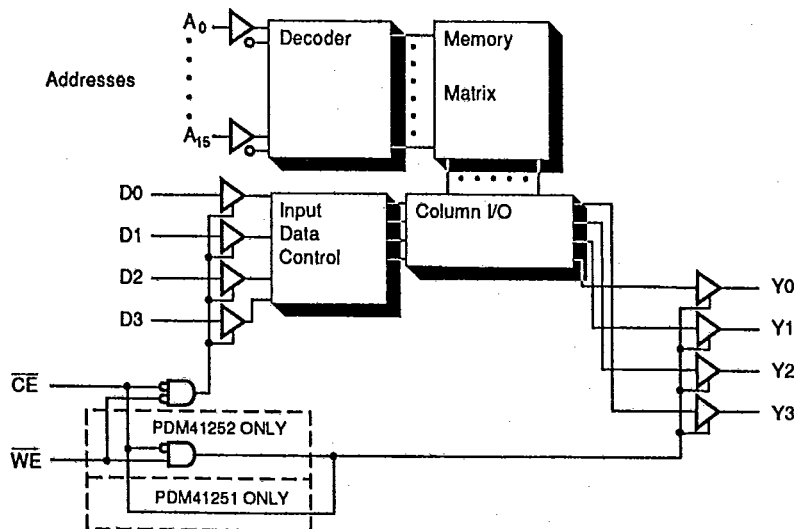
The PDM41251/2 operates from a single +5V power supply and all the inputs and outputs are fully TTL compatible. The PDM41251 and PDM41252 each comes in two versions, the standard power version PDM41251S and PDM41252S and a low power version the PDM41251L and PDM41252L. The two versions are functionally the same and only differ in their power consumption.

The Paradigm 41 (static ram) family of products are functionally equivalent to manufacturers products meeting JEDEC standards. These products are manufactured and quality controlled in the U.S.A.

The PDM41251 and PDM41252 are available in a 28-pin 300 mil DIP. The PDM41251 and PDM41252 are also available in a 28-pin LCC and a 28-pin SOJ for surface mount applications.

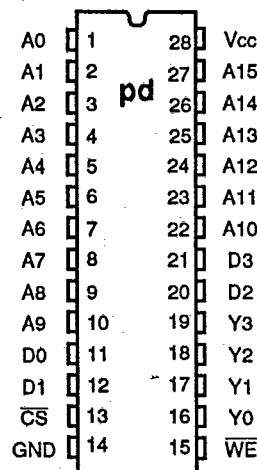
Military grade product is manufactured in compliance with the latest revision of MIL-STD-883, Rev. C, making the PDM41251 and PDM41252 ideally suited for military temperature applications.

Functional Block Diagram

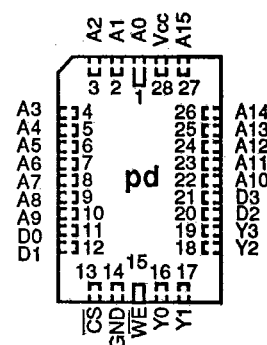


Pin Configuration

300 DIP
300 SOJ

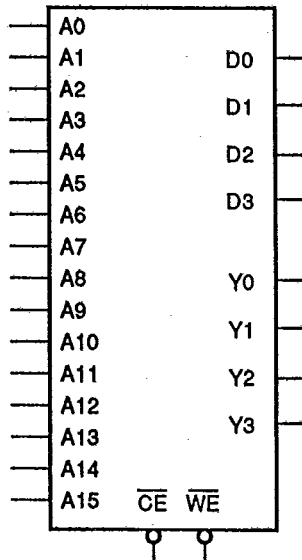


LCC



PDM41251S/L
PDM41252S/L

Logic Symbol



Recommended Operating Temperature and Supply Voltage

Grade	Ambient Temperature	GND	Vcc
Military	-55°C to +125°C	OV	5.0V ± 10%
Commercial	0°C to +70°C	OV	5.0V ± 10%

Recommended DC Operating Conditions

Symbol	Parameter	Min.	Typ.	Max.	Unit
V _{CC}	Supply Voltage	4.5	5.0	5.5	V
GND	Supply Voltage	0	0	0	V
V _{IH}	Input High Voltage	2.2	--	5.5	V
V _{IL}	Input High Voltage	-0.5 ⁽¹⁾	--	0.8	V

NOTE: 1. V_{IL}(min) = -3.0V for pulse width less than 20ns.

Absolute Maximum Ratings (1)

Symbol	Rating	Com'l.	Mil.	Unit
V _{TERM}	Terminal Voltage with Respect to GND	-0.5 to +7.0	-0.5 to +7.0	V
T _A	Operating Temperature	0 to +70	-55 to +125	°C
T _{BIAS}	Temperature Under Bias	-55 to +125	-65 to +135	°C
T _{STG}	Storage Temperature	-55 to +125	-65 to +150	°C
P _T	Power Dissipation	1.0	1.0	W
I _{OUT}	DC Output Current	50	50	mA

NOTE:

- Stresses greater than those listed under ABSOLUTE MAXIMUM RATINGS may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect reliability.

DC Electrical Characteristics

V_{CC} = 5.0V ± 10%

Symbol	Parameter	Test Conditions		PDM41251S PDM41252S		PDM41251L PDM41252L		Unit
				Min.	Max.	Min.	Max.	
I _{LI}	Input Leakage Current	V _{CC} = MAX., V _{IN} = GND to V _{CC}	MIL.	--	10	--	5	μA
			Com'l.	--	5	--	2	
I _{LO}	Output Leakage Current	V _{CC} = MAX. CE = V _{IH} , V _{OUT} = GND to V _{CC}	MIL.	--	10	--	5	μA
			Com'l.	--	5	--	2	
V _{OL}	Output Low Voltage	I _{OL} = 8mA, V _{CC} = Min. I _{OL} = 10mA, V _{CC} = Min.		--	0.4	--	0.4	V
				--	0.5	--	0.5	V
V _{OH}	Output High Voltage	I _{OH} = -4mA, V _{CC} = Min.		2.4	--	2.4	--	V

PDM41251S/L PDM41252S/L

DC Electrical Characteristics⁽¹⁾ ($V_{CC} = 5.0V \pm 10\%$, $V_{LC} \leq 0.2V$, $V_{HC} \geq V_{CC} - 0.2$)

Symbol	Parameter	Power	Function	15, ⁽⁴⁾ 20		25, 30, 35, 45, 55 ns ⁽⁵⁾		Unit
				Com'l.	MIL.	Com'l.	MIL.	
I_{CC}	Dynamic Operating Current $\overline{CE} = V_{IL}$, Outputs Open, $V_{CC} = \text{Max.}$, $f = f_{MAX}$ ⁽³⁾	S	Read	180	180	160	160	mA
			Write (2)	180	180	160	160	
		L	Read	160	160	140	140	mA
			Write (2)	160	160	140	140	
I_{SB}	Standby Power Supply Current (TTL Level) $\overline{CE} \geq V_{IH}$, $V_{CC} = \text{Max.}$, Outputs Open $f = f_{MAX}$ (3)	S	—	60	60	60	60	mA
		L	—	50	50	50	50	mA
I_{SB1}	Full Standby Power Supply Current (CMOS Level) $\overline{CE} \geq V_{HC}$, $V_{CC} = \text{Max.}$, $f = 0$ ⁽³⁾ $V_{IN} \geq V_{HC}$ or $\leq V_{LC}$	S	—	30	30	30	30	mA
		L	—	10	10	10	10	mA

NOTES:

1. All values are maximum guaranteed values.
2. Write cycle current specifications are included to aid in the design of extremely sensitive applications. It should be noted that in most systems the ratio of read cycles to write cycles is extremely high. When comparing these figures to those on other data sheets, we recommend that the read cycle data is used (especially where "Average" current consumption figures are specified).
3. At $f = f_{MAX}$ address and data inputs are cycling at the maximum frequency of read cycles of $1/t_{RC}$. $f = 0$ means no input lines change.
4. This speed grade is available in Commercial grade product only.
5. This speed grade is available in Military grade product only.

Capacitance⁽¹⁾ ($T_A = +25^\circ\text{C}$, $f = 1.0 \text{ MHz}$)

Symbol	Parameter	Conditions	Max	Unit
C_{IN}	Input Capacitance	$V_{IN} = 0V$	10	pf
C_{OUT}	Output Capacitance	$V_{OUT} = 0V$	10	pf

NOTE 1: This parameter is determined by device characterization but is not production tested.

AC Test Conditions

Input pulse levels.....GND to 3.0V
Input rise and fall times.....5ns
Input timing reference levels.....1.5V
Output reference levels.....1.5V
Output load.....See figures 1 and 2

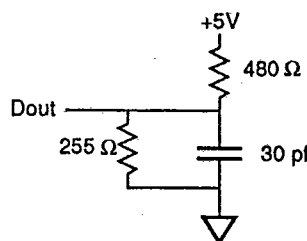


Fig. 1 Output Load
Equivalent

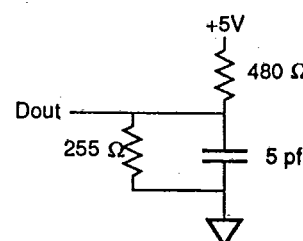
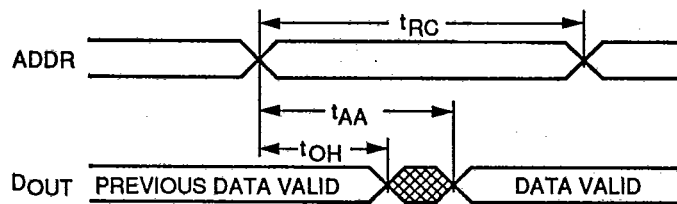


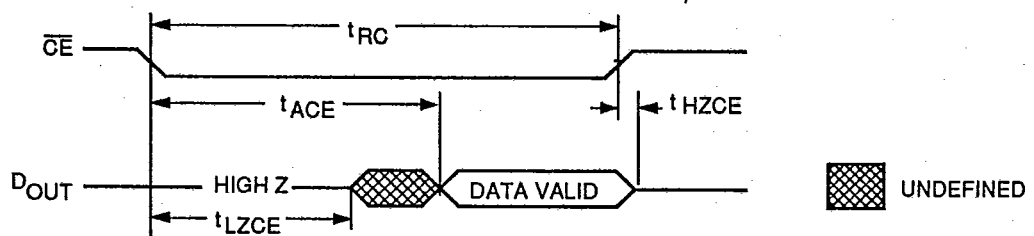
Fig. 2 Output Load
Equivalent (for t_{ZCE} ,
 t_{HZCE} , t_{LWE} , t_{HWE})

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Read Cycle No. 1 (6, 7)



Read Cycle No. 2 (3, 6, 8)



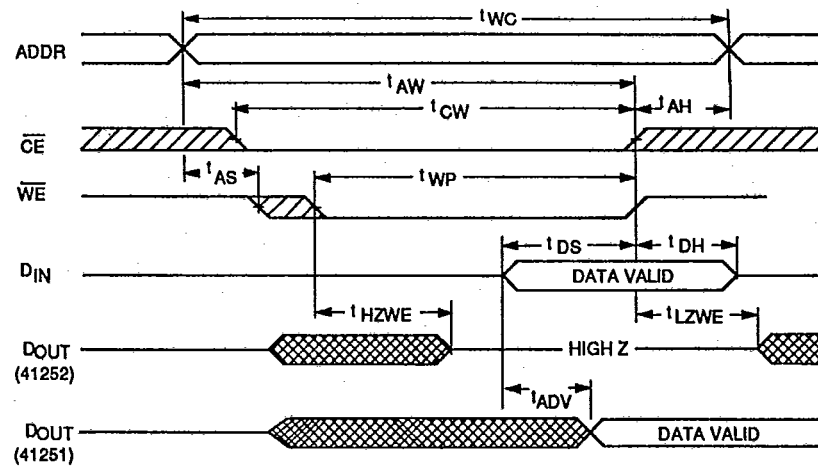
AC Electrical Characteristics $V_{CC} = 5V \pm 10\%$, All Temperature Ranges

Description		-15 (9)	-20	-25	-35	-45	-55 (10)		
READ Cycle		Min	Max	Min	Max	Min	Max	Min	Max
READ cycle time	t_{RC}	15		20		25		35	
Address access time	t_{AA}		15		20		25		35
Chip enable access time	t_{ACE}		15		20		25		35
Output hold from address change	t_{OH}	3		3		5		5	
Chip enable to output in low Z (4)	t_{LZCE}	5		5		5		5	
Chip disable to output in high Z (2, 3, 4)	t_{HZCE}		10		10		15		20
Chip enable to power up time (4)	t_{PU}	0		0		0		0	
Chip disable to power down time (4)	t_{PD}		15		20		25		35

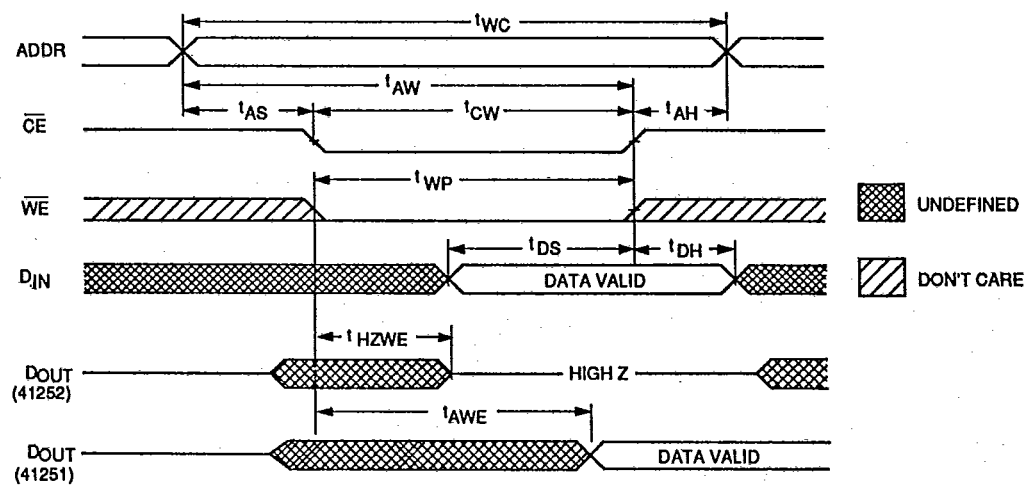
NOTE : reference page 6 for all notes on this page

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Write Cycle No. 1
(Write Enable Controlled)



Write Cycle No. 2
(Chip Enable Controlled)

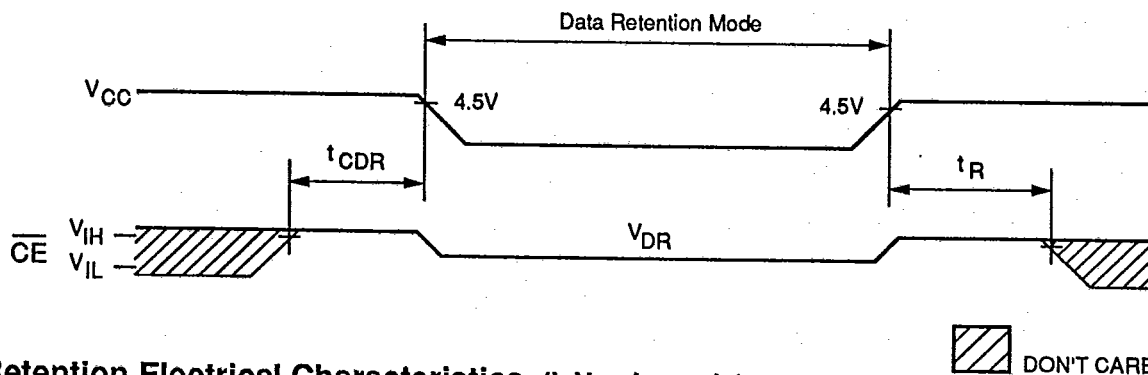


AC Electrical Characteristics $V_{CC} = 5V \pm 10\%$, All Temperature Ranges

Description		-15 (9)		-20		-25		-35		-45		-55 (10)		Units
WRITE Cycle	Sym	Min	Max	Min	Max	Min	Max	Min	Max	Min	Max	Min	Max	
WRITE cycle time (4)	t_{WC}	15		20		25		35		45		55		ns
Chip enable to end of write (4)	t_{CW}	15		20		20		30		40		50		ns
Address Valid to end of write	t_{AW}	15		20		20		30		40		50		ns
Address set-up time	t_{AS}	0		0		0		0		0		0		ns
Address hold from end of write	t_{AH}	0		0		0		0		0		0		ns
Write pulse width	t_{WP}	15		20		20		25		30		35		ns
Data set-up time	t_{DS}	10		12		12		15		20		25		ns
Data hold time	t_{DH}	0		0		0		0		0		0		ns
Write disable to output in low Z (4) (41252)	t_{LZWE}	0		0		0		0		0		0		ns
Write enable to output in high Z (4) (41252)	t_{HZWE}		5		8		10		13		20		25	ns
Write enable to data valid (41251)	t_{AWE}		15		20		20		30		35		40	ns
Data valid to output valid (41251)	t_{ADV}		15		20		20		30		35		40	ns

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Low V_{CC} Data Retention Waveform



Data Retention Electrical Characteristics (L Version only)

Symbol	Parameter	Test Conditions	Min.	Typ.	Max	Unit
V_{DR}	V_{CC} for Retention Data		2	—	—	V
I_{CCDR}	Data Retention Current	$\overline{CE} \geq V_{CC} - 0.2V$ $V_{IN} \geq V_{CC} - 0.2V$ or $\leq 0.2V$	$V_{CC} = 2V$	—	95	μA
			$V_{CC} = 3V$	—	350	μA
t_{CDR}	Chip Deselect to Data Retention Time		0	—	—	ns
$t_R^{(4)}$	Operation Recovery Time		$t_{RC}^{(5)}$	—	—	ns

NOTES: (For pages 4,5 and 6)

1. Test conditions as specified with the output loading circuit as shown in Fig #1 unless otherwise noted.
2. T_{HZCE} and T_{HZWE} are tested with $C_L = 5pF$ as shown in Fig. #2. Transition is measured $\pm 200mV$ from steady state voltage.
3. At any given temperature and voltage condition, T_{HZCE} is less than T_{LZCE} .
4. This parameter is sampled.
5. t_{RC} = Read cycle time.
6. $\overline{WE}$ is high for a READ cycle.
7. The device is continuously selected. All the Chip Enables are held in their state
8. The address is valid prior to or coincident with the latest occurring Chip Enable.
9. $0^\circ C$ to $+70^\circ C$ temperature range only.
10. $-55^\circ C$ to $+125^\circ C$ temperature range only.

Truth Table ⁽¹⁾ ($V_{LC}=0.2V$, $V_{HC}=V_{CC}-0.2V$)

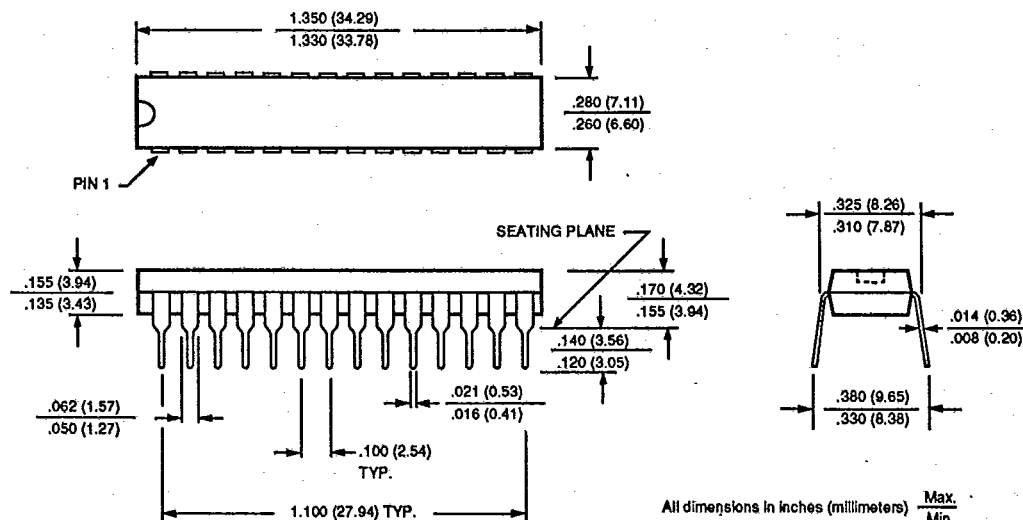
$\overline{WE}$	$\overline{CE}$	I/O	MODE
X	H	Hi-Z	Standby
H	L	D _{OUT}	Read
L	L	D _{IN}	Write (2)
L	L	Hi-Z	Write (3)

NOTE:

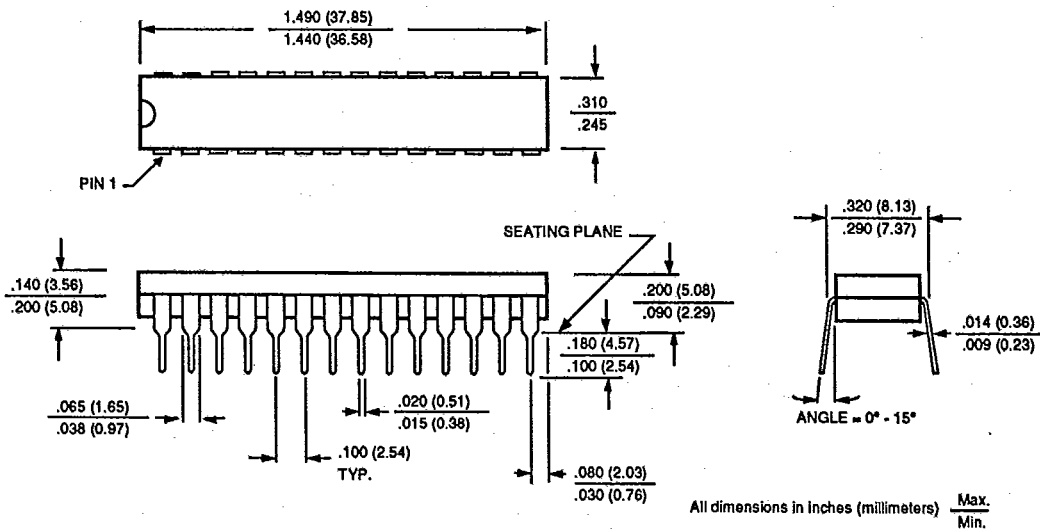
1. H = V_{IH} , L = V_{IL} , X = DON'T CARE.
2. For PDM41251 only.
3. For PDM41252 only.

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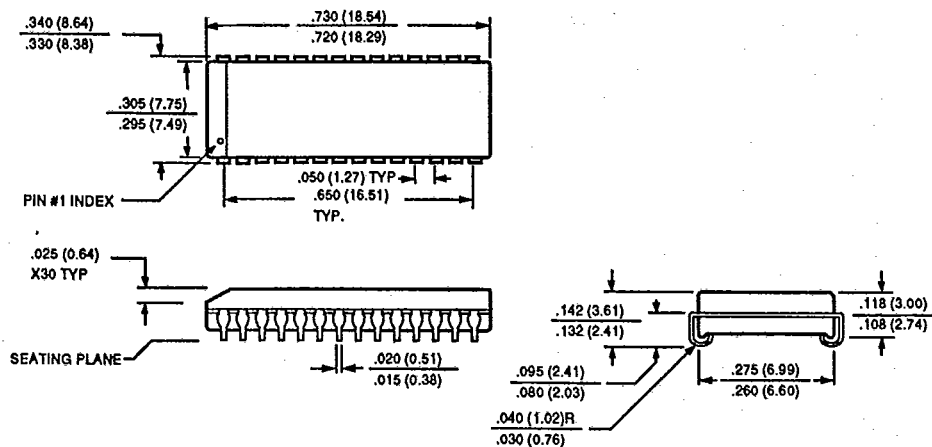
28 Pin Plastic Dip



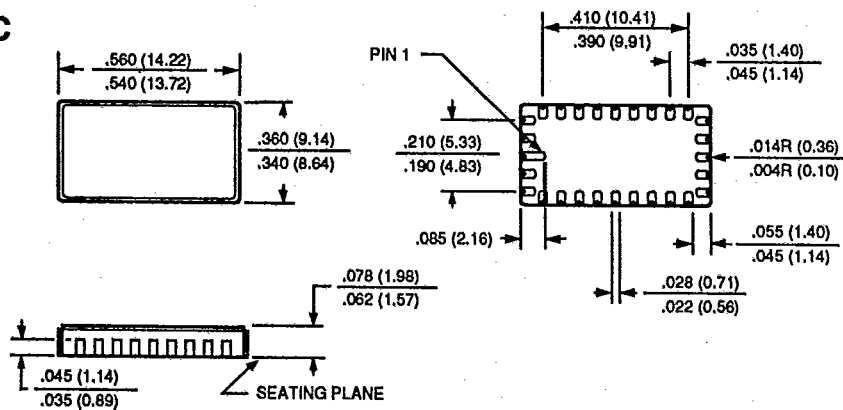
28 Pin Cerdip



28 Pin Plastic SOJ



28 Pin LCC



All dimensions in inches (unless noted). All dimensions in inches (millimeters.) $\frac{\text{Max.}}{\text{Min.}}$

Ordering Information

PDM	Device Type	Power	Speed	Package	Process/Temperature Range
					Blank Commercial (0° to +70°C)
					M Military (-55°C to +125°C)
					B Military (-55°C to +125°C)
					Compliant to MIL-STD 883
				P	300 mil Plastic Dip
				D	300 mil Cerdip
				L28	350 x 550 LCC
				SO	300 mil Plastic SOJ
				15	Commercial Only
				20	
				25	
				35	
				45	
				55	Military Only
				S	Standard Power
				L	Low Power
				41251	
				41252	
					256K (64K x 4) Static RAM with separate I/O